



STP40NF12

N-channel 120V - 0.028Ω - 40A TO-220
Low gate charge STripFET™ II Power MOSFET

General features

| Type | V _{DSS} | R _{DS(on)} | I _D |
|-----------|------------------|---------------------|----------------|
| STP40NF12 | 120V | <0.032Ω | 40A |

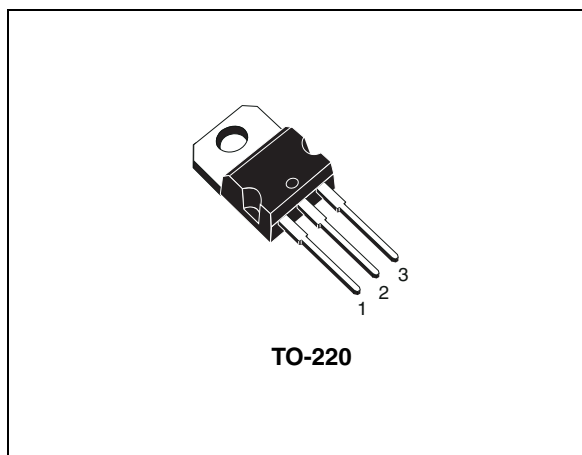
- Exceptional dv/dt capability
- 100% avalanche tested
- Application oriented characterization

Description

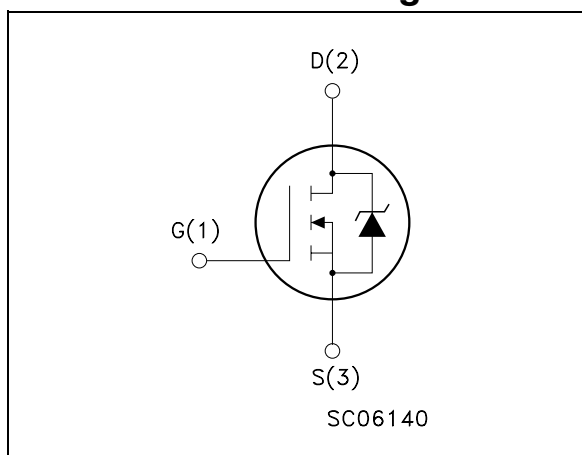
This Power MOSFET series realized with STMicroelectronics unique STripFET process has specifically been designed to minimize input capacitance and gate charge. It is therefore suitable as primary switch in advanced high-efficiency isolated DC-DC converters for Telecom and Computer application. It is also intended for any application with low gate charge drive requirements.

Applications

- Switching application



Internal schematic diagram



Order codes

| Part number | Marking | Package | Packaging |
|-------------|---------|---------|-----------|
| STP40NF12 | P40NF12 | TO-220 | Tube |

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1 Electrical ratings

Table 1. Absolute maximum ratings

| Symbol | Parameter | Value | Unit |
|----------------|---|-------------|------|
| V_{DS} | Drain-source voltage ($v_{GS} = 0$) | 120 | V |
| V_{GS} | Gate- source voltage | ± 20 | V |
| I_D | Drain current (continuous) at $T_C = 25^\circ\text{C}$ | 40 | A |
| I_D | Drain current (continuous) at $T_C = 100^\circ\text{C}$ | 28 | A |
| $I_{DM}^{(1)}$ | Drain current (pulsed) | 160 | A |
| P_{TOT} | Total dissipation at $T_C = 25^\circ\text{C}$ | 150 | W |
| | Derating factor | 1 | W/°C |
| $dv/dt^{(2)}$ | Peak diode recovery voltage slope | 14 | V/ns |
| $E_{AS}^{(3)}$ | Single pulse avalanche energy | 150 | mJ |
| T_{stg} | Storage temperature | - 55 to 175 | °C |
| T_j | Max. operating junction temperature | | |

1. Pulse width limited by safe operating area
2. $I_{SD} \leq 40\text{A}$, $di/dt \leq 600\text{A}/\mu\text{s}$, $V_{DD} \leq V_{(BR)DSS}$, $T_j \leq T_{JMAX}$.
3. Starting $T_j = 25^\circ\text{C}$, $I_D = 40\text{A}$, $V_{DD} = 50\text{V}$

Table 2. Thermal data

| | | | |
|----------------|--|------|------|
| $R_{thj-case}$ | Thermal resistance junction-case Max | 1 | °C/W |
| R_{thj-a} | Thermal resistance junction-ambient Max | 62.5 | °C/W |
| T_l | Maximum lead temperature for soldering purpose | 300 | °C |

2 Electrical characteristics

($T_{CASE}=25^{\circ}C$ unless otherwise specified)

Table 3. On/off states

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|---------------|--|--|------|-------|-----------|--------------------|
| $V_{(BR)DSS}$ | Drain-source Breakdown voltage | $I_D = 250 \mu A, V_{GS} = 0$ | 120 | | | V |
| I_{DSS} | Zero gate voltage Drain current ($V_{GS} = 0$) | $V_{DS} = \text{Max rating}$ $V_{DS} = \text{Max rating}, T_C = 125^{\circ}C$ | | | 1 10 | μA μA |
| I_{GSS} | Gate-body leakage current ($V_{DS} = 0$) | $V_{GS} = \pm 20V$ | | | ± 100 | nA |
| $V_{GS(th)}$ | Gate threshold voltage | $V_{DS} = V_{GS}, I_D = 250 \mu A$ | 2 | 2.8 | 4 | V |
| $R_{DS(on)}$ | Static drain-source on resistance | $V_{GS} = 10V, I_D = 20A$ | | 0.028 | 0.032 | Ω |

Table 4. Dynamic

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|----------------|------------------------------|--|------|------|------|------|
| $g_{fs}^{(1)}$ | Forward transconductance | $V_{DS} = 25V, I_D = 20A$ | | 40 | | S |
| C_{iss} | Input capacitance | | | 1880 | | pF |
| C_{oss} | Output capacitance | $V_{DS} = 25V, f = 1 \text{ MHz},$ $V_{GS} = 0$ | | 265 | | pF |
| C_{rss} | Reverse transfer capacitance | | | 110 | | pF |
| Q_g | Total gate charge | | | 60 | 80 | nC |
| Q_{gs} | Gate-source charge | $V_{DD} = 80V, I_D = 40A,$ $V_{GS} = 10V$ | | 11 | | nC |
| Q_{gd} | Gate-drain charge | | | 21 | | nC |

1. Pulsed: Pulse duration = 300 μs , duty cycle 1.5.

Table 5. Switching times

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|--------------|---------------------|---|------|------|------|------|
| $t_{d(on)}$ | Turn-on delay time | $V_{DD} = 50V, I_D = 20A$ $R_G = 4.7 \Omega, V_{GS} = 10V$ (see Figure 13) | | 28 | | ns |
| t_r | Rise time | | | 63 | | ns |
| $t_{d(off)}$ | Turn-off-delay time | $V_{DD} = 50V, I_D = 20A,$ $R_G = 4.7 \Omega, V_{GS} = 10V$ (see Figure 13) | | 84 | | ns |
| t_f | Fall time | | | 28 | | ns |

Table 6. Source drain diode

| Symbol | Parameter | Test conditions | Min. | Typ. | Max | Unit |
|-----------------|-------------------------------|---|------|------|-----|------|
| I_{SD} | Source-drain current | | | | 40 | A |
| $I_{SDM}^{(1)}$ | Source-drain current (pulsed) | | | | 160 | A |
| $V_{SD}^{(2)}$ | Forward on voltage | $I_{SD} = 40A, V_{GS} = 0$ | | | 1.3 | V |
| t_{rr} | Reverse recovery time | $I_{SD} = 40A, V_{DD} = 25V$ $di/dt = 100A/\mu s,$ $T_j = 150^\circ C$ (see Figure 15) | | 114 | | ns |
| Q_{rr} | Reverse recovery charge | | | 456 | | nC |
| I_{RRM} | Reverse recovery current | | | 8 | | A |

1. Pulse width limited by safe operating area.

2. Pulsed: Pulse duration = 300 μs , duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

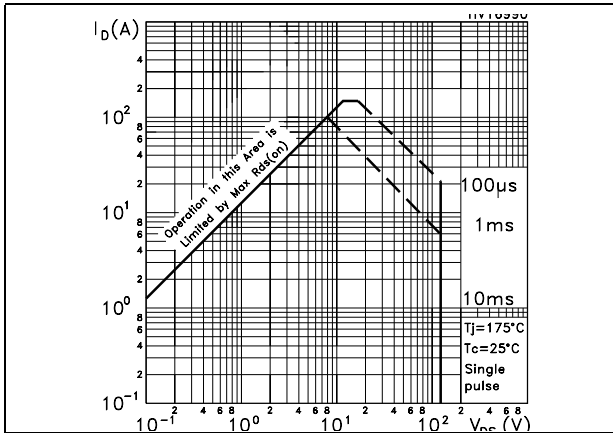


Figure 2. Thermal impedance

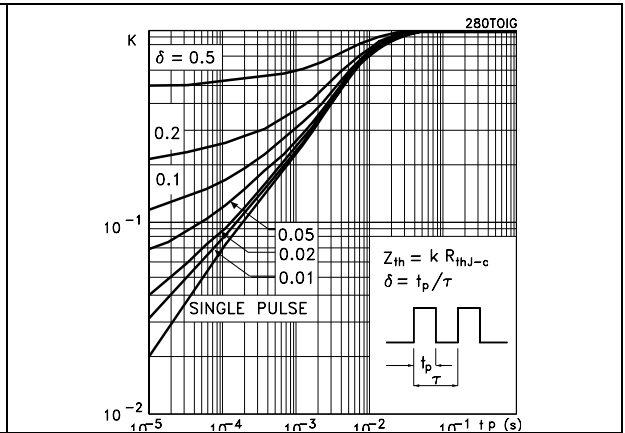


Figure 3. Output characteristics

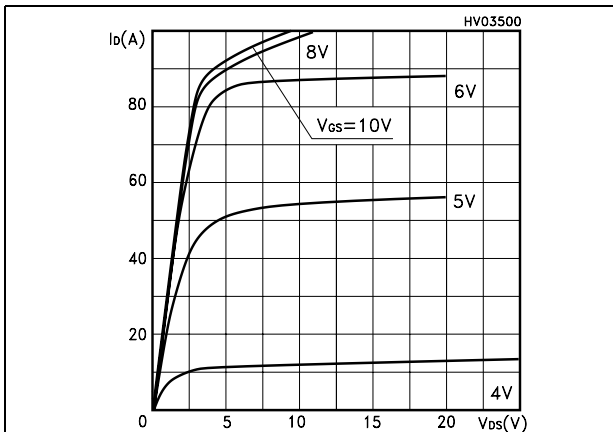


Figure 4. Transfer characteristics

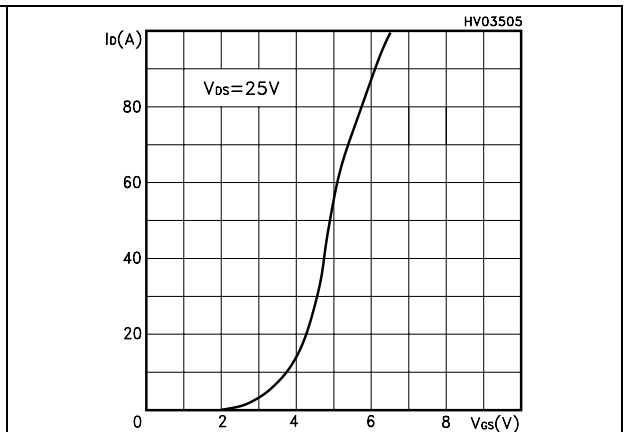


Figure 5. Transconductance

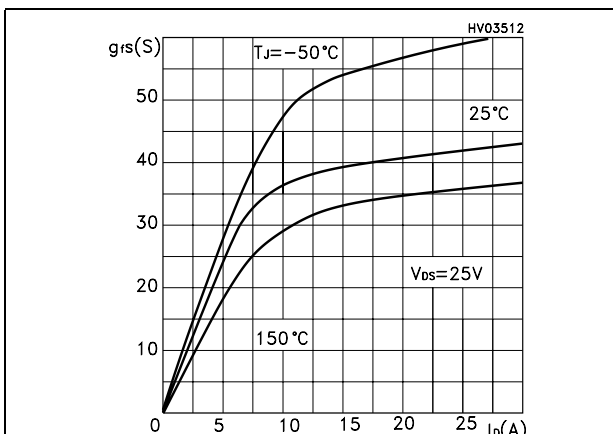


Figure 6. Static drain-source on resistance

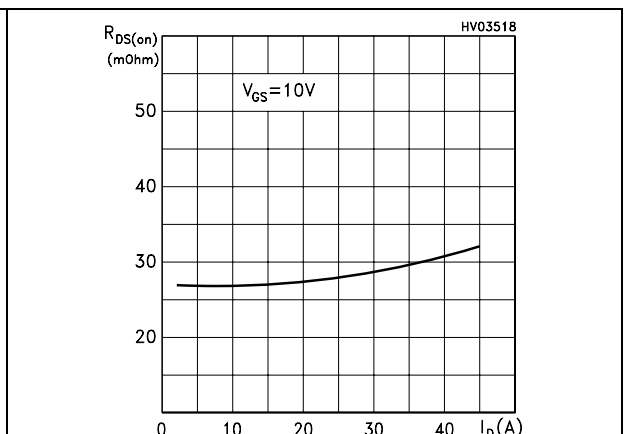


Figure 7. Gate charge vs. gate-source voltage Figure 8. Capacitance variations

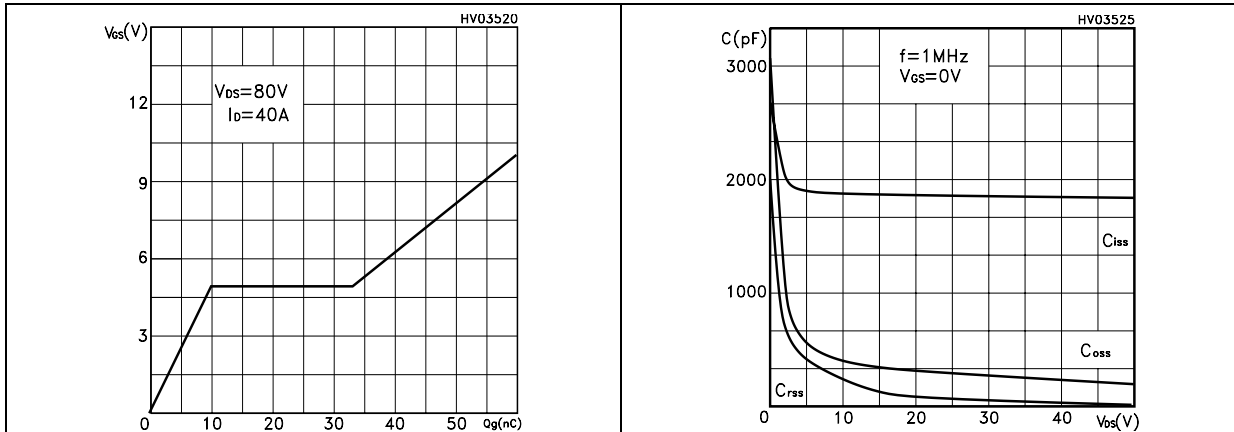


Figure 9. Normalized gate threshold voltage vs. temperature Figure 10. Normalized on resistance vs. temperature

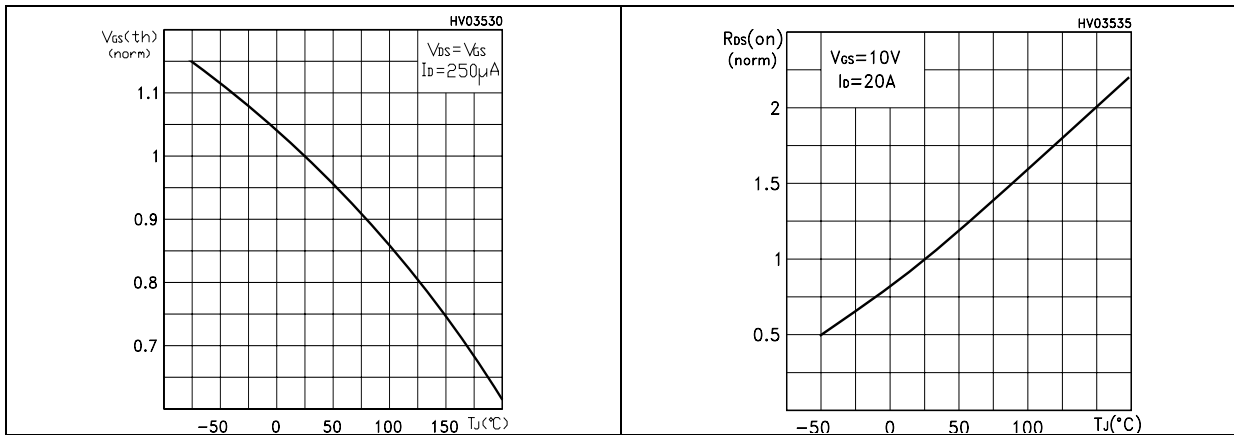
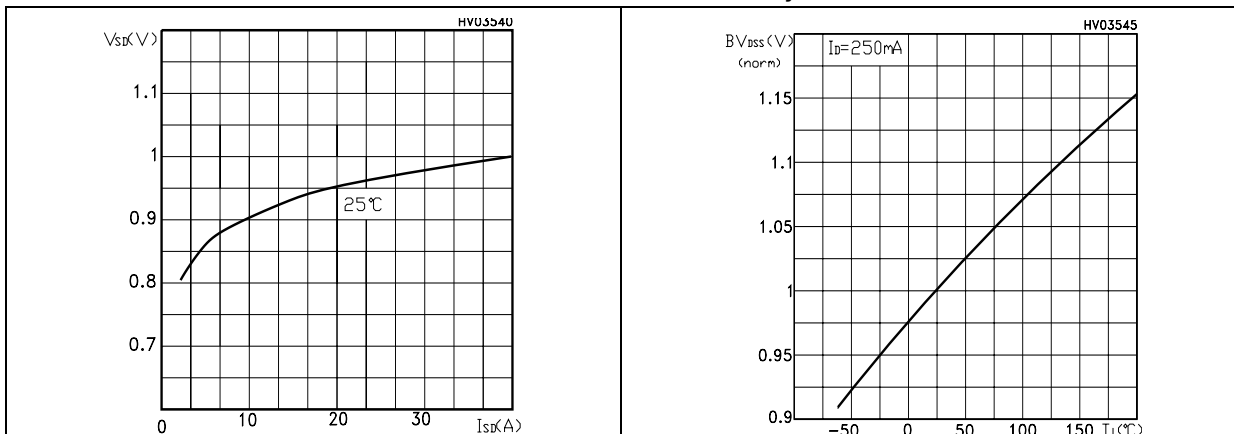


Figure 11. Source-drain diode forward characteristics Figure 12. Normalized breakdown voltage vs. t_j



3 Test circuit

Figure 13. Switching times test circuit for resistive load

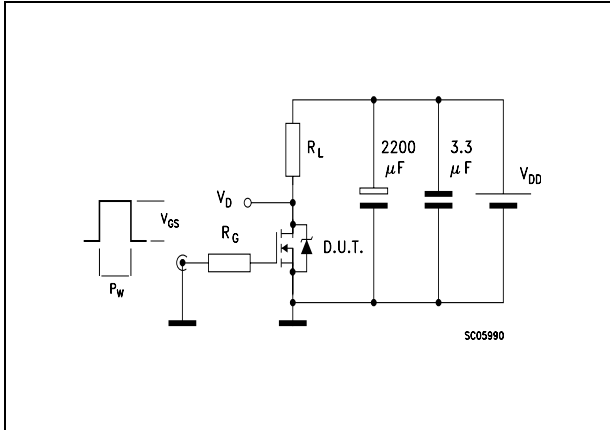


Figure 14. Gate charge test circuit

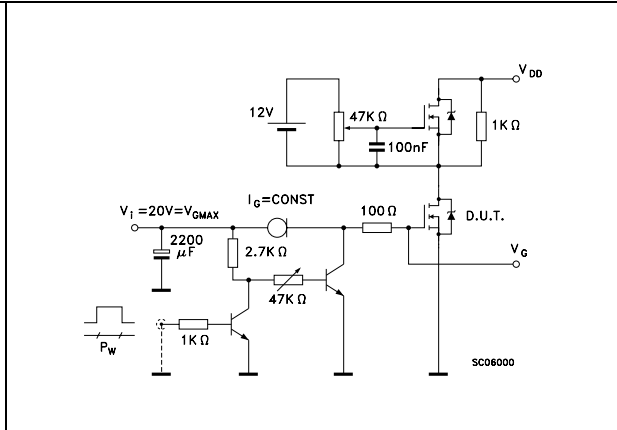


Figure 15. Test circuit for inductive load switching and diode recovery times

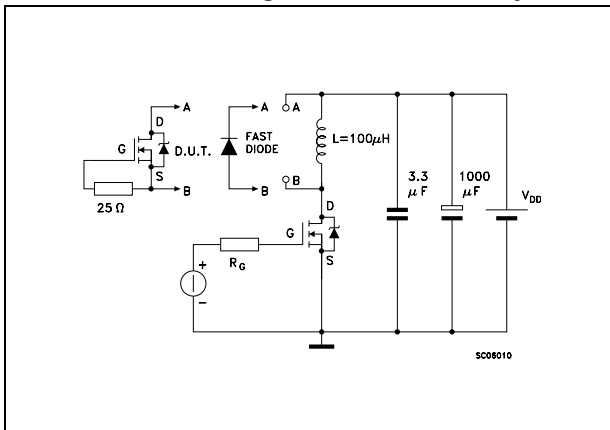


Figure 16. Unclamped Inductive load test circuit

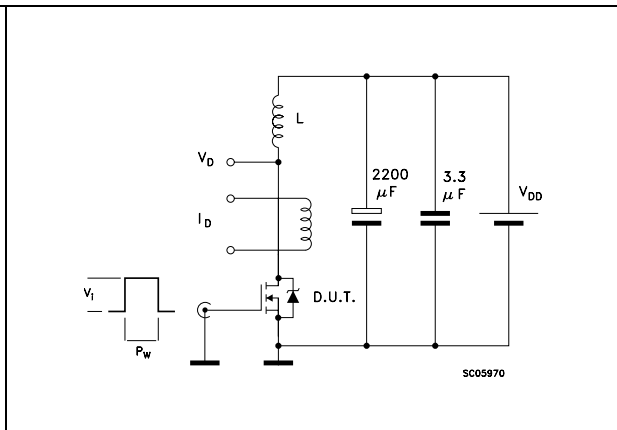


Figure 17. Unclamped inductive waveform

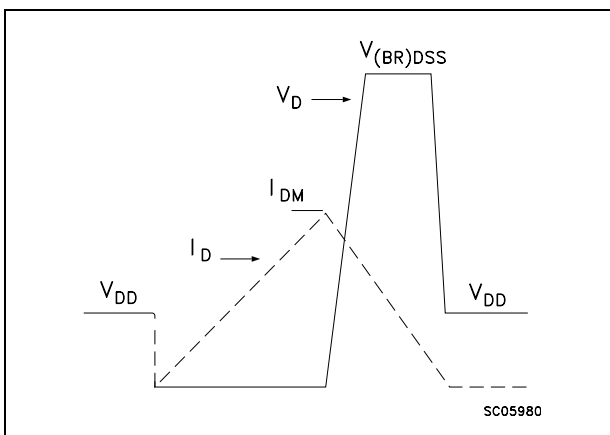
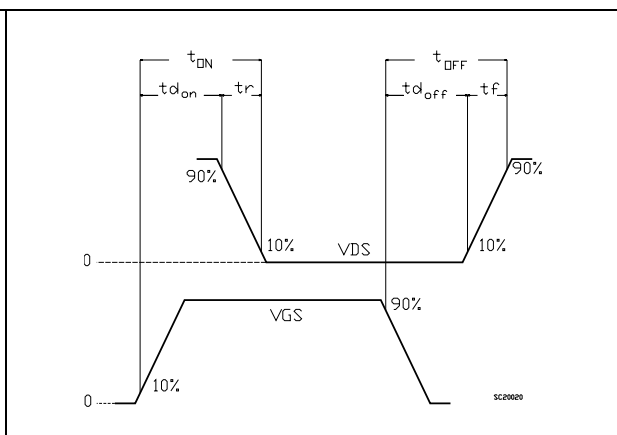


Figure 18. Switching time waveform

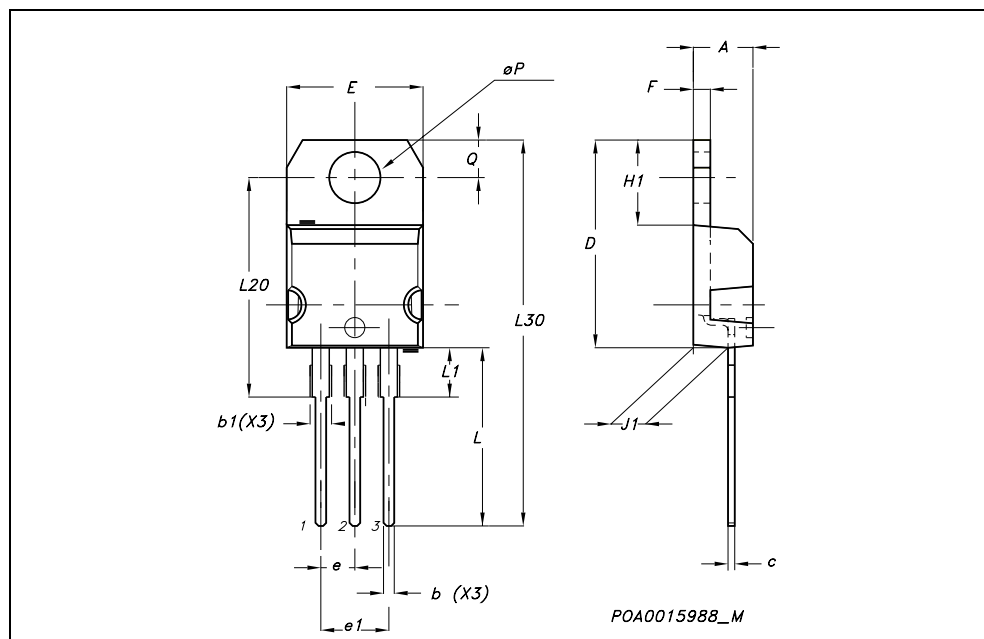


4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at : www.st.com

TO-220 MECHANICAL DATA

| DIM. | mm. | | | inch | | |
|------|-------|-------|-------|-------|-------|-------|
| | MIN. | TYP. | MAX. | MIN. | TYP. | MAX. |
| A | 4.40 | | 4.60 | 0.173 | | 0.181 |
| b | 0.61 | | 0.88 | 0.024 | | 0.034 |
| b1 | 1.15 | | 1.70 | 0.045 | | 0.066 |
| c | 0.49 | | 0.70 | 0.019 | | 0.027 |
| D | 15.25 | | 15.75 | 0.60 | | 0.620 |
| E | 10 | | 10.40 | 0.393 | | 0.409 |
| e | 2.40 | | 2.70 | 0.094 | | 0.106 |
| e1 | 4.95 | | 5.15 | 0.194 | | 0.202 |
| F | 1.23 | | 1.32 | 0.048 | | 0.052 |
| H1 | 6.20 | | 6.60 | 0.244 | | 0.256 |
| J1 | 2.40 | | 2.72 | 0.094 | | 0.107 |
| L | 13 | | 14 | 0.511 | | 0.551 |
| L1 | 3.50 | | 3.93 | 0.137 | | 0.154 |
| L20 | | 16.40 | | | 0.645 | |
| L30 | | 28.90 | | | 1.137 | |
| øP | 3.75 | | 3.85 | 0.147 | | 0.151 |
| Q | 2.65 | | 2.95 | 0.104 | | 0.116 |



5 Revision history

Table 7. Revision history

| Date | Revision | Changes |
|-------------|----------|---|
| 09-Sep-2004 | 1 | First version. |
| 17-Aug-2006 | 2 | The document has been reformatted. |
| 31-Jan-2007 | 3 | Typo mistake on Table 1 . |

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